

THE PERSON NAMED IN COLUMN TWO IS NOT THE PERSON NAMED IN COLUMN TWO IS NAM HPF-10-02-T-S **HPF SERIES**

(5,08 mm) .200"

POWER SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPF

Insulator Material: Black LCP

Contact Material:

BeCu

Plating:

Sn over 50μ" (1,27 μm) Ni

Insertion Depth: (3,68 mm) .145" to (8,26 mm) .325" (.368" (9,35 mm) plus

board thickness minimum for bottom entry)
Wiping Distance:

(0,38 mm) .015" Insertion Force:

(Single contact only) 56 oz (15,57 N) avg.

Withdrawal Force: (Single contact only) 52 oz (14,46 N) avg. Lead–Free Solderable:

SMT Lead Coplanarity: (0,15 mm) .006" max (02-10) (0,20 mm) .008" max (11-20)

RoHS Compliant:

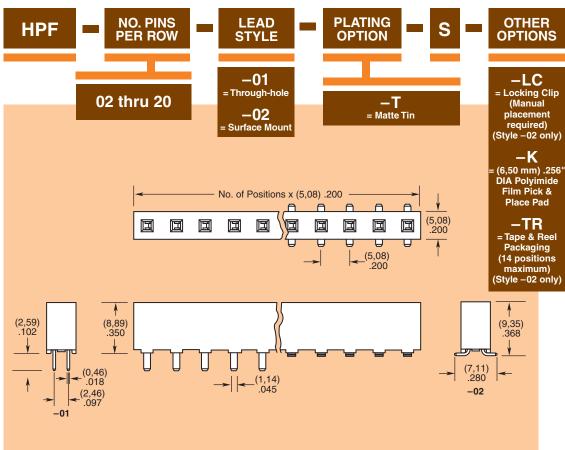
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality





Surface Mount Mates with: or HPM, HPW Through-hole CONTACT HPF/HPM **CURRENT RATING** PINS (PER CONTACT) GGEDIZED 16.6 A 2 14.4 A (5,08 mm) 3 13.2 A Three-finger .200" pitch 4 12.7 A Power Eye contact Locking clip option



Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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